





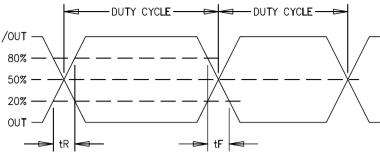
Electrical Specifications:

Parameter	Symbol	Min.	Тур.	Max.	Units	Conditions
Frequency of Operation	Fo		1080.000000		MHz	
			Frequency Sta	bility		
Frequency Stability	ΔF/F	-50		+50	ppm	Includes initial tolerance, deviation over operating temperature, variations to supply voltage, load, vibration, shock and 1st year aging.
Aging		-5		+5	ppm	1 st year
			RF Outpu	t		
Output Type		L۱	/PECL Compatib	ole		
Output Load		50	Ω to (Vcc-2) VD	C	V	
Symmetry (duty cycle)	T _{DC}	45		55	%	Ref. to 50% of waveform
Logic Level "1"		V _{cc} -1.02			V	
Logic Level "0"				V _{cc} -1.63	V	
Rise/Fall Time	T _R /T _F			0.5	nS	From 20% to 80% V _{DD}
Start-up Time T _{SU}				10	mS	$T_{amb} = +25^{\circ}C$
		Supply Vo	oltage & Powe	r Consum	ption	
Operating Voltage	Vcc	3.135	3.3	3.465	V	
Supply Current	Icc			130	mA	
			Other Parame	ters		
Phase Jitter (RMS)	ΦЈ		220	300	fsec	12KHz to 20MHz

Enable/Disable Function:

Pad 1	Output Pad #4, #5
High or Open	
0.8 Vcc Min	Output Enabled
0.5 V Max	Output Disabled to high-Z

Output Waveform:









Environmental & Packaging Requirements:

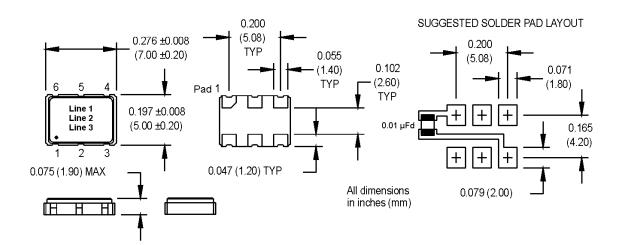
	<u></u>	<u>.gq.</u>	### OTTION	4-				
Operating Temperature	T _A	-40		+85	°C			
Storage Temperature	Ts	-55		+125	°C			
Mechanical Shock	Per MIL-STD-202, Method 213, Condition C (100 g's, 6 ms duration, ½ sinewave)							
Vibration	Per MIL-STD-202, Method 201 & 204 (10 g's from 10-2000 Hz)							
Thermal Cycle	Per MIL-S	Per MIL-STD-883, Method 1010, B (-55°C to 125°C, 15 min. dwell, 10 cycles)						
Hermeticity	Per MIL-STD-202, Method 112 (1 x 10 ⁻⁸ atm cc/s of Helium)							
Moisture Sensitivity	MSL 1							
Level (MSL)	WISL I							
Solderability	Per EIAJ-STD-002							
Max. Soldering	See solder profile, Figure 1							
Conditions		i profile, Fi	ille, rigule i					
Package Type 6-pad 5.0 X 7.0 X 1.9 mm leadless cer				ceramic. Ro	oHS complian	nt.		

Dimensions, Marking, Pin Out:

Pad	Function
1	Enable/Disable
2	N/C
3	Ground
4	Output
5	Complimentary Output
6	+V _{cc}

Part Marking					
Line 1	M2100S124				
Line 2	1080M0000				
Line 3	MPTI yyww				

	Legend			
уу	Year			
ww	Work Week			

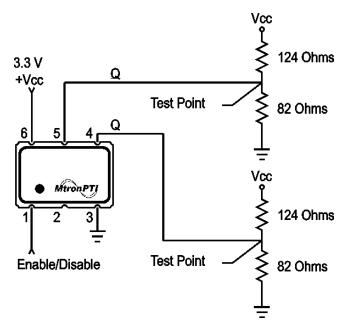


Typical Test Circuit & Load Circuit Diagrams:









Soldering Conditions:

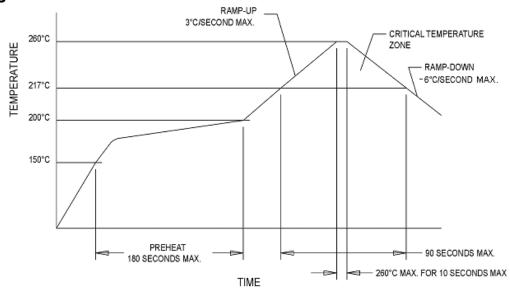


Figure 1

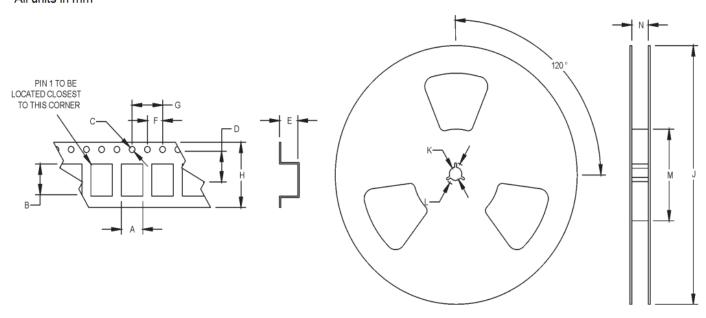
Tape and Reel Specifications:







All units in mm



Tape and Reel Specifications											
Α	В	С	D	Е	F	G	Н	J	K	L	М
5.32	7.28	1.5	7.5	2.2	4	8	16	178	13.5	24.8	80

Datasheet Revision Table:

Butachiot Novicion Table:									
Date	Rev.	Author	Details of Revision						
3/04/15	0	MM	Original release.						